

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20180621001 Datasheet for TS3A5018 Change Notification

Date: July 03, 2018

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is a notice of change to a product data sheet for a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN www admin team@list.ti.com).

Sincerely,

PCN Team SC Business Services

Data Sheet Change Notification Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE TS3A5018PW TS3A5018DBQR TS3A5018PWR TS3A5018RSVR **CUSTOMER PART NUMBER**

null null null null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180621			001		PCN Date:		July 3, 2018	
Title: Datasheet for TS3A5018									
Customer Contact:	PCN Manager							pt:	Quality Services
Proposed 1 st Ship Da	te:	Octob	er 3	3, 2018					,
Change Type:				•					
Assembly Site			Design				Wafer	· Bump Site	
Assembly Process			□ Data Sheet □ Data Sheet					· Bump Material	
Assembly Materials				Part number change					Bump Process
Mechanical Specification				Test Site				Wafer	· Fab Site
Packing/Shipping/Labeling			Test Process				Wafer	Fab Materials	
							Wafer	Fab Process	
Notification Details									
Description of Change:									
Texas Instruments Incorporated is announcing an information only notification.								on.	
The product datasheet(s) is l	peing ι	ıpda	ated as sum	marize	ed below.			
ŢEXAS									
INSTRUMENTS							cone	400L IAN	TS3A5018
							SCDS	109H –JAN	NUARY 2005-REVISED MAY 2018
Changes from Revision G (March 2015) to Revision H Page									
Changed the pinout images									
 Changed the r_{on} MAX value at 25°C From: 8 Ω To: 17 Ω in the Electrical Characteristics for 1.8-V Supply table									
Changed the fon Wild Vall	ac at i	uli i ioiii.	14.0	0 32 10. 02 32 11	I die Lie	otriour Orial	doten	0000 101	7.0-V Supply table
The datasheet number	will b	e chan	gind	J.					
Device Family			Change From:					Change To:	
TS3A5018			SCDS189G					SCDS189H	
http://www.ti.com/product/TS3A5018									
III.(p.//www.ti.com/product/155A5016									
Reason for Change:									
To accurately reflect device characteristics.									
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):									
Electrical specification performance changes as indicated above.									
Changes to product identification resulting from this PCN:									
None.									
Product Affected:									
TS3A5018D	TS	3A501	8DE	3QR	TS3A	5018DBC	RE4	Т	S3A5018DBQRG4
TS3A5018DE4		3A501				5018DR			S3A5018DRE4
TS3A5018PW		3A501				5018PWF	₹		S3A5018PWRE4
TS3A5018RGYR	_	3A501				5018RSVR			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com

Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com